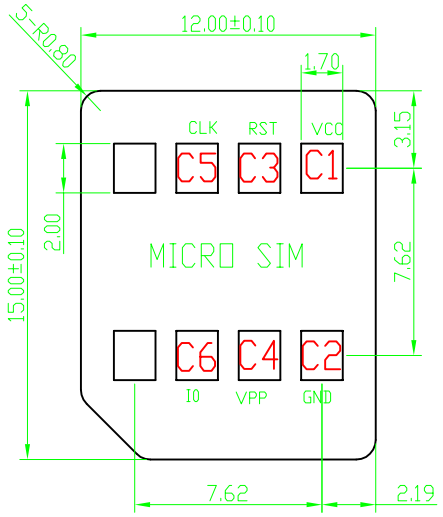
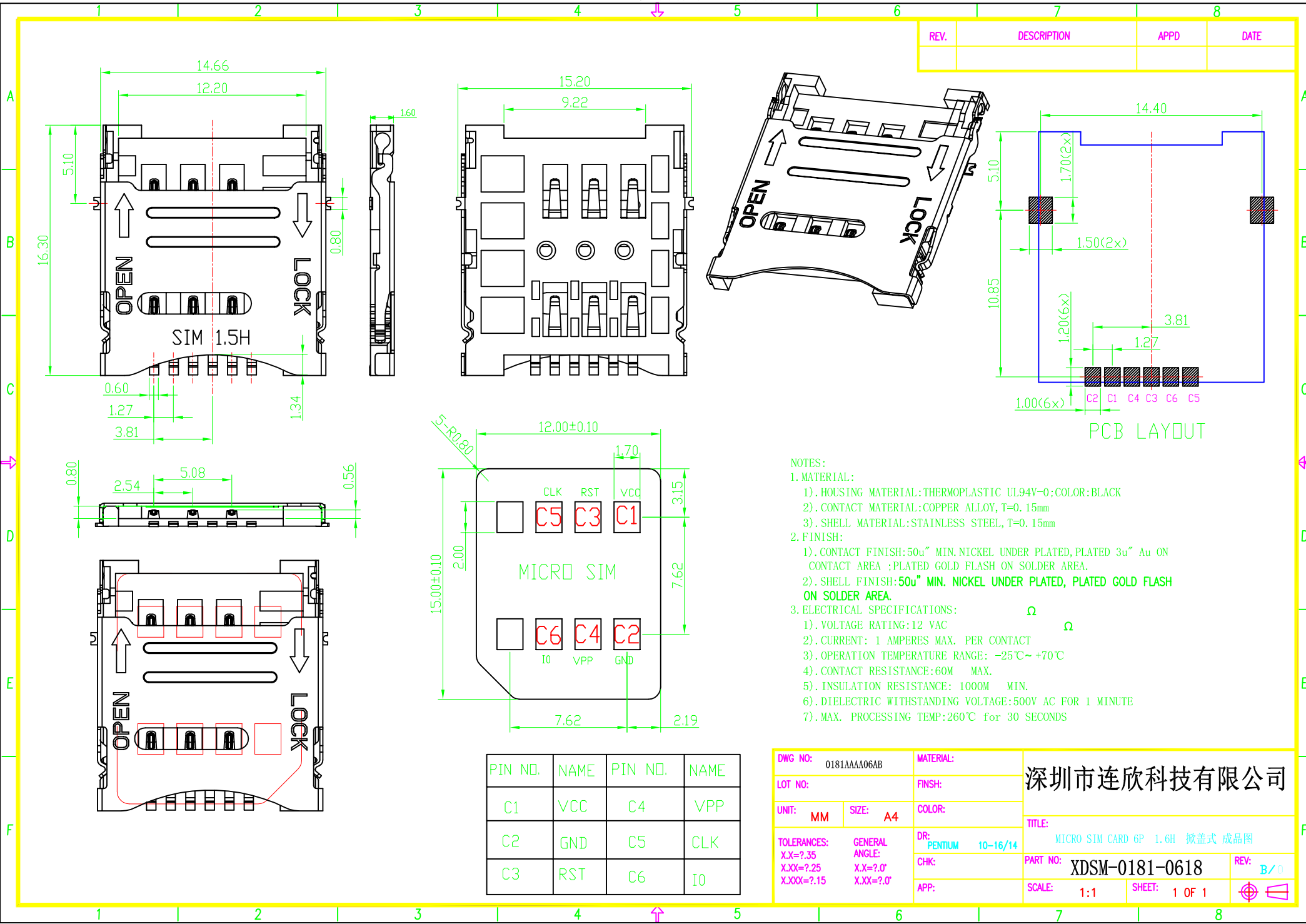
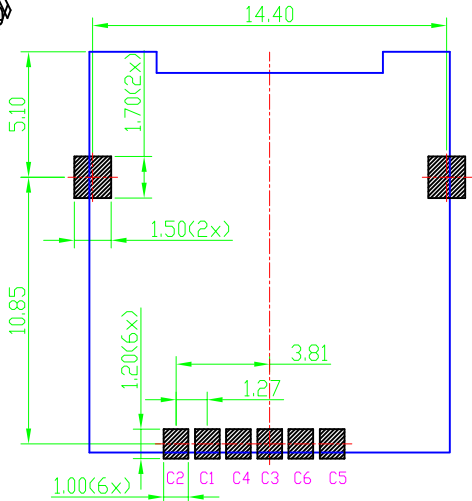
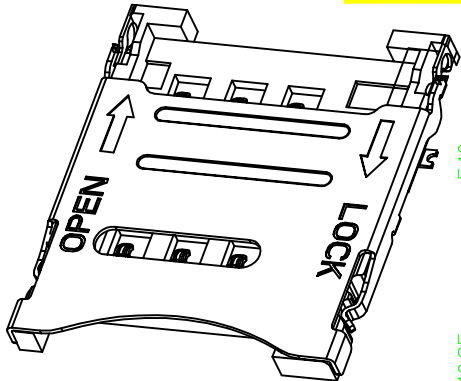


REV.	DESCRIPTION	APPD	DATE



PIN NO.	NAME	PIN NO.	NAME
C1	VCC	C4	VPP
C2	GND	C5	CLK
C3	RST	C6	I/O



PCB LAYOUT

- NOTES:
- MATERIAL:
    - HOUSING MATERIAL: THERMOPLASTIC UL94V-0; COLOR: BLACK
    - CONTACT MATERIAL: COPPER ALLOY, T=0.15mm
    - SHELL MATERIAL: STAINLESS STEEL, T=0.15mm
  - FINISH:
    - CONTACT FINISH: 50u" MIN. NICKEL UNDER PLATED, PLATED 3u" Au ON CONTACT AREA ; PLATED GOLD FLASH ON SOLDER AREA.
    - SHELL FINISH: 50u" MIN. NICKEL UNDER PLATED, PLATED GOLD FLASH ON SOLDER AREA.
  - ELECTRICAL SPECIFICATIONS:
    - VOLTAGE RATING: 12 VAC
    - CURRENT: 1 AMPERES MAX. PER CONTACT
    - OPERATION TEMPERATURE RANGE: -25°C ~ +70°C
    - CONTACT RESISTANCE: 60M MAX.
    - INSULATION RESISTANCE: 1000M MIN.
    - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE
    - MAX. PROCESSING TEMP: 260°C for 30 SECONDS

DWG NO: 0181AAAA06AB		MATERIAL:	
LOT NO:		FINISH:	
UNIT: MM	SIZE: A4	COLOR:	
TOLERANCES: X.X=? .35 X.XX=? .25 X.XXX=? .15		DR: PENTUM 10-16/14	
GENERAL ANGLE: X.X=? .0' X.XXX=? .0'		CHK:	
APP:		APP:	

深圳市连欣科技有限公司

TITLE: MICRO SIM CARD 6P 1.6H 掀盖式 成品图			
PART NO: XDSM-0181-0618		REV: B/0	
SCALE: 1:1	SHEET: 1 OF 1		

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